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What is claimed is:

1. A photosensitive resin composition comprising as a component (A) a green colorant of the formula

in which the rings A, B, C and D are substituted by hydroxy or by the moiety

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$$(CR_1R_2)_n$$
 , wherein R_1 is hydrogen or C_1 - C_4 -Alkyl, R_2 is hydrogen or C_1 - C_4 -Alkyl,

n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C_1 - C_6 alkyl, C_1 - C_6 alkoxy, hydroxy, NHCOR₃, NHSO₂R₄ or SO₂NHR₅, wherein R₃ is C_1 - C_4 -Alkyl or phenyl, R₄ is C_1 - C_4 -Alkyl or phenyl,

- b) as a component (B) an alkali soluble oligomer or polymer (reactive or unreactive),
- c) as a component (C) a polymerizable monomer,
- d) as a component (D) a photoinitiator.
- e) as a component (E) an epoxy compound, and also, if desired,
- f) as a component (F) further additives.
- 2. A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula

3. A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula

- 4. Solder resist process using the photosensitive resin composition according to any one of claims 1 to 3, which process comprises the steps of
- (1) mixing the components (A) to (E) and if desired (F),
- (2) applying the resulting composition to the substrate ("coating of the substrate"),
- (3) evaporating of the solvent, if present, at a temperature between 80-90°C,
- (4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,

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- (5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas, and
- (6) thermally curing the sample at a temperature about 150°C, thereby initiating the cross-linking between the carboxylic acid and the epoxy component.
- 5. Coated substrate obtained by the process according to claim 4.
- 6. Substrate coated with the photosensitive resin composition according to any of claims 1 to 3.